

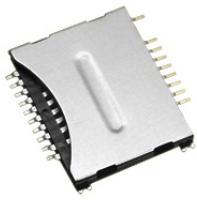
Operation: 超薄抽拉型 Push-pull & MICRO-SD4.0+UFS SOCKETS



LTEM NO.:UFS-405 (多合一高速读/写卡座)

(10.7L×13.56W×1.3H & UFS+TF Sockets)

MEMORY-CARD-SOCKETS



Technical parameter

双排贴装 SMT

PROJECT	LEVEL	A[better product]		B[average product]	
Electrical Properties	Contact Rating	50mA, 24V DC			
	Initial Contact Resistance	50mΩ max.		80mΩ max.	
	Insulation Resistance	100MΩ min.500V DC			
	Withstand Voltage	500V AC for 1 minute		350 V AC for 1 minut	
Durable Performance	There No Load	5,000 Cycles		3,500 Cycles	
	Rated Load	3,500 Cycles		2,500 Cycles	
	Storage temp.	-25℃~+85℃(Operating Temp:)			

側向導入 LATERAL

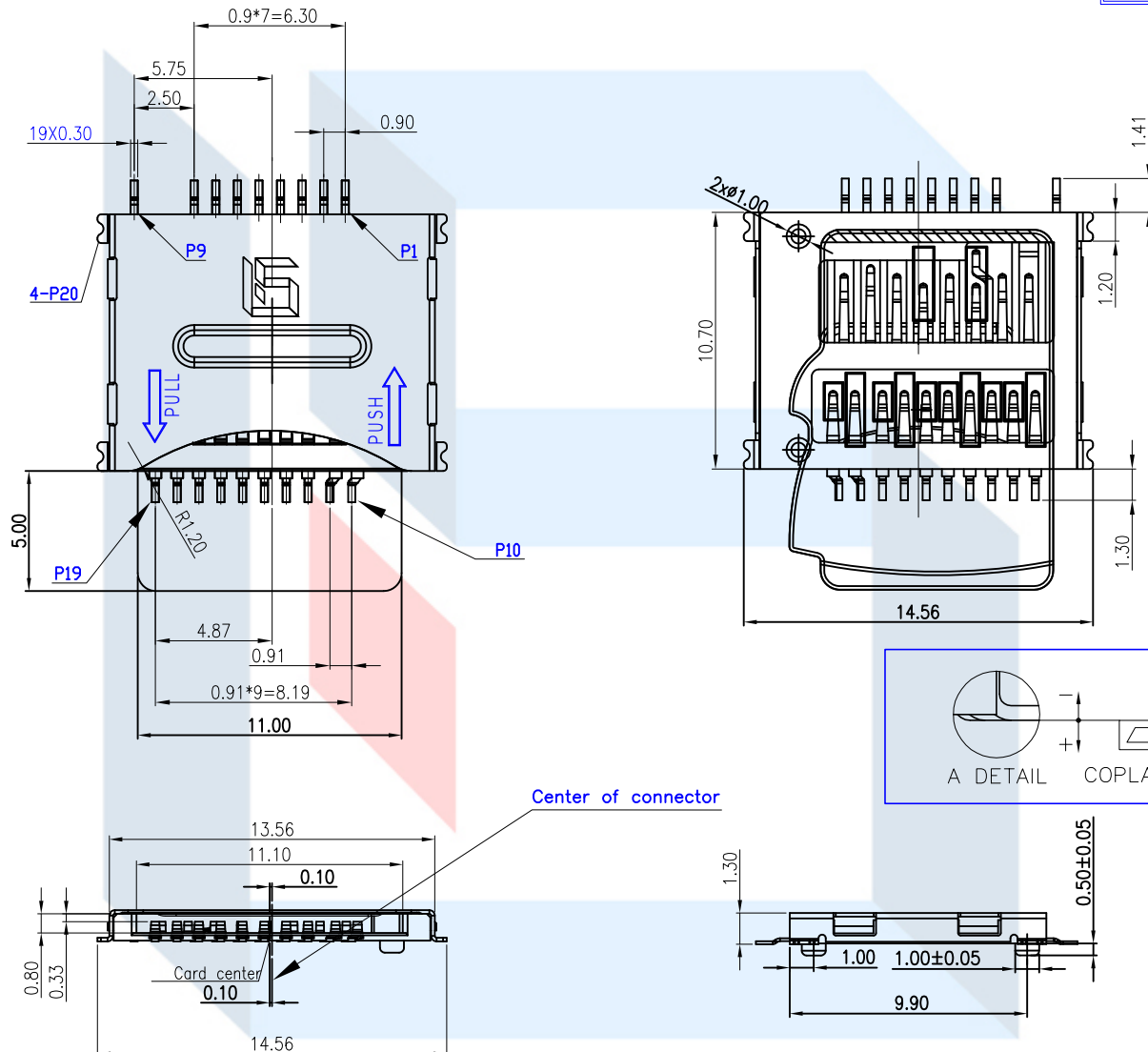
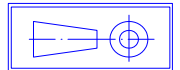
精密部品 NICETY

可靠 STABILIZE

適合環保 RoHS

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Unit:mm

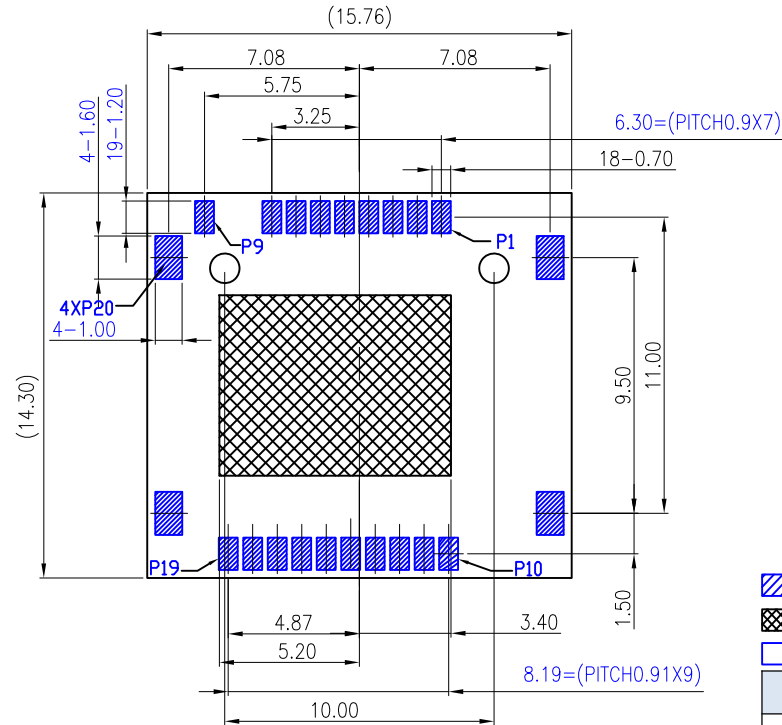


Operating Force

Inward 3.0~5.0N. (1N.=100gram-force)
 Exiting 3.0~5.0N. (1N.=100gram-force)

Solder-ability (Max.)

IR Reflow: 255°C, 5sec. Manual: 350°C, 3sec.

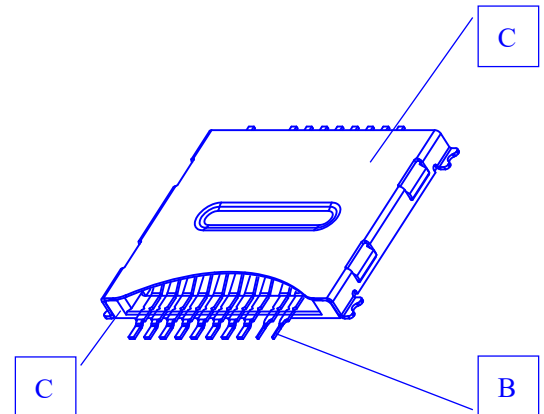
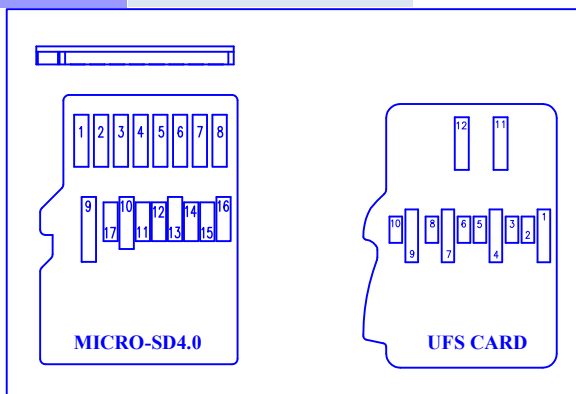


- PAD AREA
- VIA AND TRACE KEEPOUT
- OTHER COMPONENT KEEPOUT

DECIMALS	ANGLES
X : ±0.30	X° : ±3°
X.X : ±0.20	X.X° : ±1°
X.XX : ±0.15	X.XX° : ±0.5°

CARD

MICRO-SD4.0 / UFS CARD



Material declaration

NAME	MATERIAL	PLATING
A 基体 HOUSING	LCP 30%G/F (Black)耐热塑胶 UL 94V-0	SET
B 接触端子 CONTACT	C5210R-H (t=0.12mm)磷铜 【Au G/F PLATING OVER Ni】 SOLDER TAIL AREA:MATTE TIN 80~100u" OVER Ni	G/F
C 外壳 SHELL	C2680(t=0.15mm)BASS 黄铜 SOLDER ABLE AREA 【Ni PLATING OVER ALL】	-

本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。Products do not belong to hazardous waste, When waste can recycling processing

運送時本產品不要直接與水、酸鹼性化學物質接觸,或放置於含有以上氣體環境中,並且需要注意會有滑落、側翻的危險發生; 運輸過程中不能有碰撞或者擠壓,須保證溫度與濕度適中 [常溫 25°C, 濕度在 50°C 以內], 不可導致材料變形或氧化。

注記 NOTICE

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Pin define

Connector PinNo.	MicroSD 4.0 Card Pin No.	Micro SD with UHS-II and SWIO support			UFS Card	
		Name	Type	Description	Card Pin No.	Name
P1	P1	DAT2	I/O	Data Line[Bit 2]		
P2	P2	CD/DAT3	I/O	Card Detect/Data Line[Bit 3]		
P3	P3	CMD	I/O	Command/Response		
P4	P4	V _{DD1}	S	Supply voltage(3.3V)	P12	VCC
P5	P5	CLK	I	Clock		
P6	P6	V _{SS}	S	Supply voltage ground	P11	VSS
P7	P7	DAT0/RCLK+	I/O	Data Line[Bit 0]/RCLK+		
P8	P8	DAT1/RCLK-	I/O	Data Line[Bit 1]/RCLK-		
P9		CD				CD
P10					P10	C/D(GND)
P11	P9	V _{DD2}	S	Supply voltage(1.8V)	P9	VCCQ2
P12	P17	SWIO	I	Single Wire Protocol Interface	P8	REF_CLK
P13	P10	V _{SS}	S	Supply voltage ground	P7	VSS
P14	P11	D0+	I/O	UHS-II D0+	P6	DOUT_T
P15	P12	D0-	I/O	UHS-II D0-	P5	DOUT_C
P16	P13	V _{SS}	S	Supply voltage ground	P4	VSS
P17	P14	D1-	I/O	UHS-II D1-	P3	DIN_T
P18	P15	D1+	I/O	UHS-II D1+	P2	DIN_C
P19	P16	V _{SS}	S	Supply voltage ground	P1	VSS
P20	GND		GROUND		GND	GROUND

手焊接时

项目	条件
焊接温度	350°C max.
连续焊接时间	3s max.
焊剂斗容量	60W max.

Please practice according to below condition:

- (1) Preheat : 150 °C 90-120s
- (2) Soldering heat : 260 °C Max 10S.
- (3) Immersion depth: Up to the surface of the board

自动浸焊时

项目	条件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷电路板焊接面的周围温度 100°C max.
预热温度时间	60s max.
焊接温度	255°C max.
焊接浸渍时间	5s max.
焊接次数	2次以下

